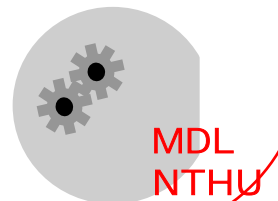


Table of contents

- 1 Introduction**
- 2 Basic IC fabrication processes**
- 3 Fabrication techniques for MEMS**
- 4 Applications of MEMS**
- 5 Mechanics issues of MEMS**



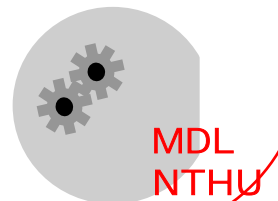
Chapter 1. Introduction

1.0 IC and MEMS

1.1 Terminology and general informations

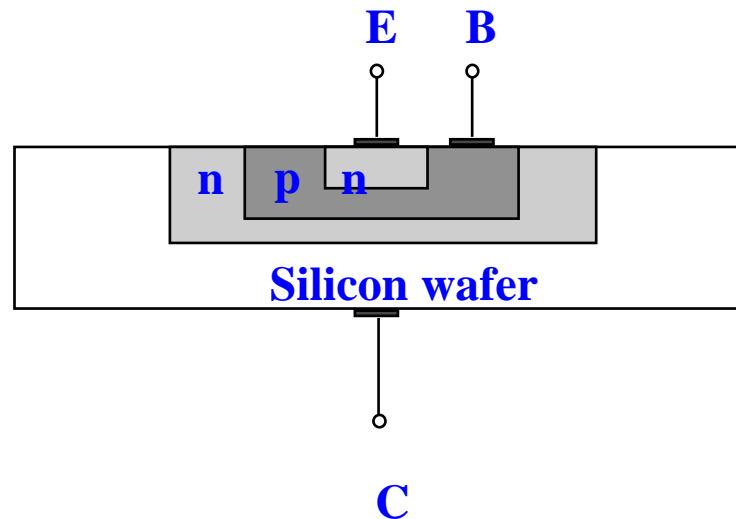
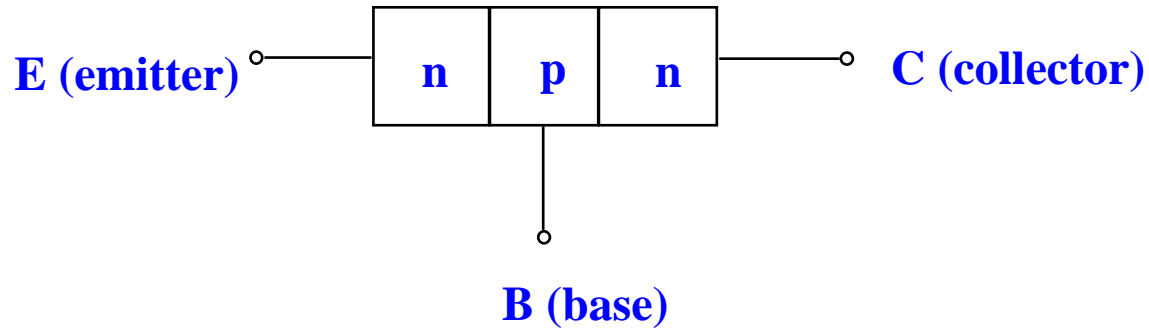
1.2 Historical background

1.3 MEMS at Taiwan

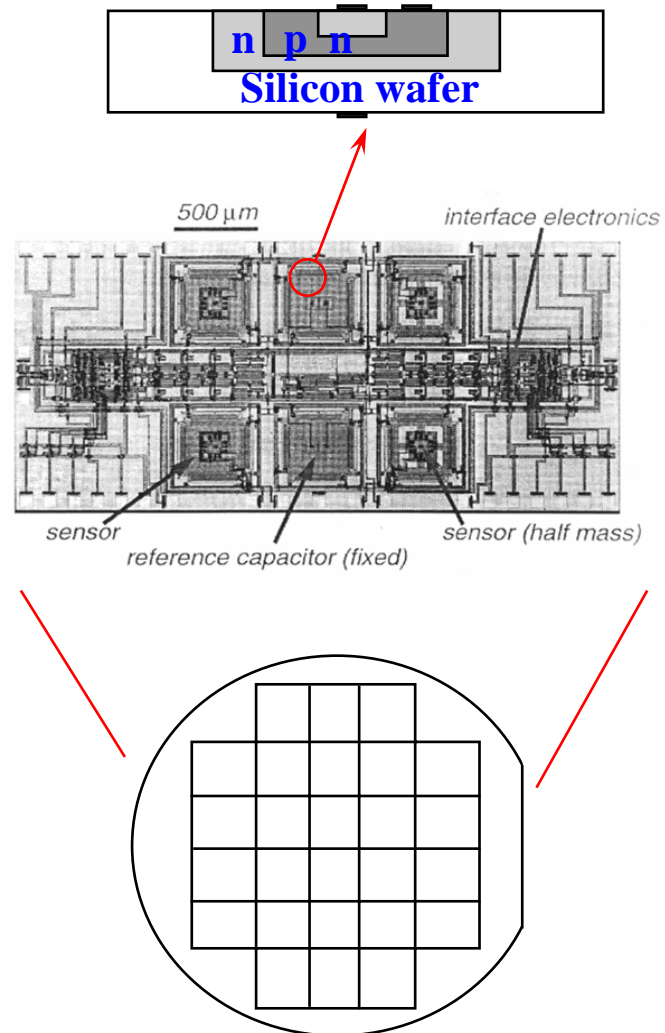


1.0 IC and MEMS

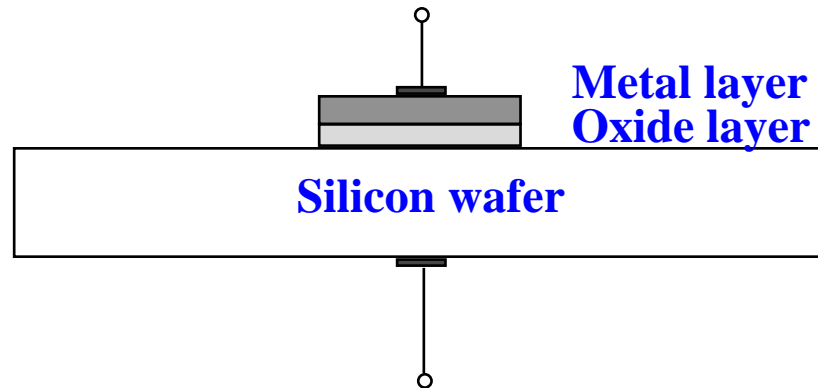
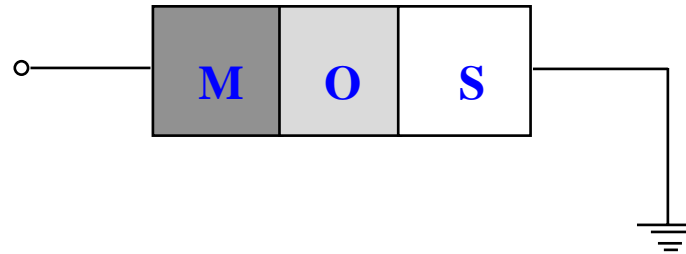
- **BJT (Bipolar Junction Transistor)**



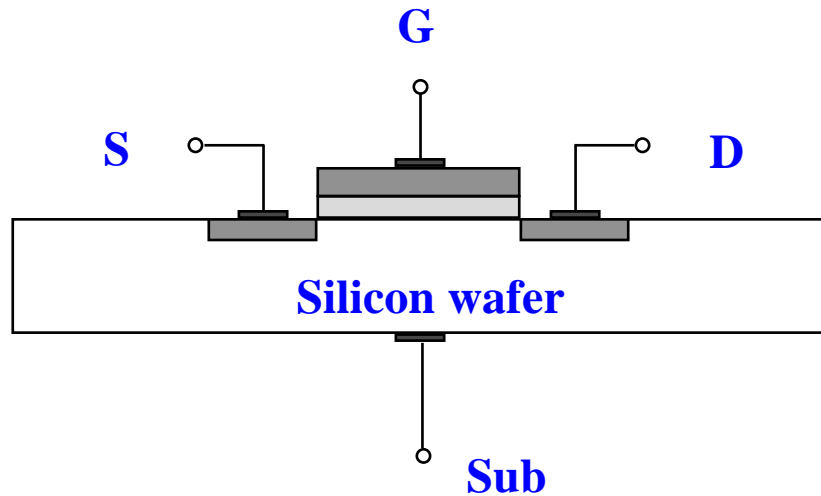
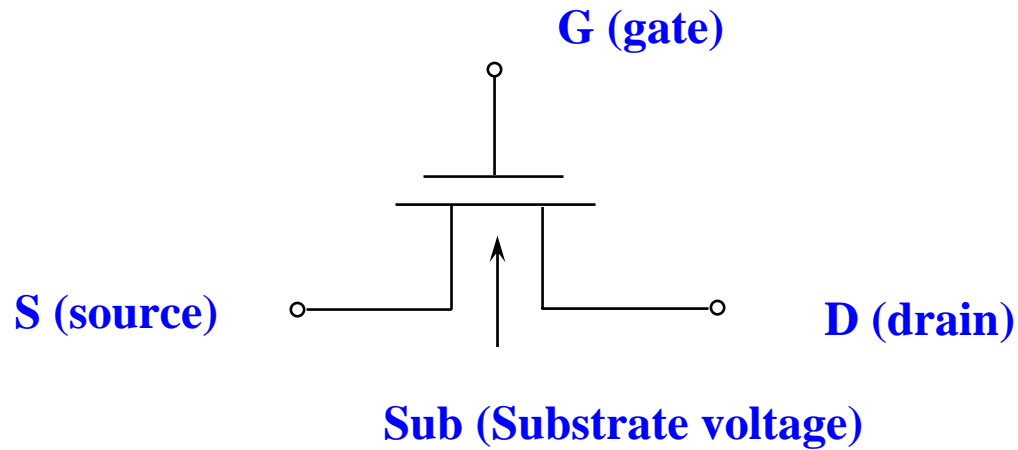
- A global view of an electronic component on a wafer



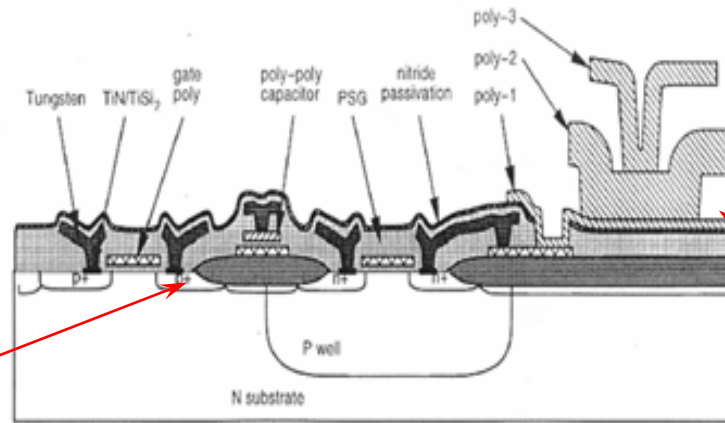
- **MOS (Metal Oxide Semiconductor) Capacitor**



- **MOS (Metal Oxide Semiconductor) Transistor**

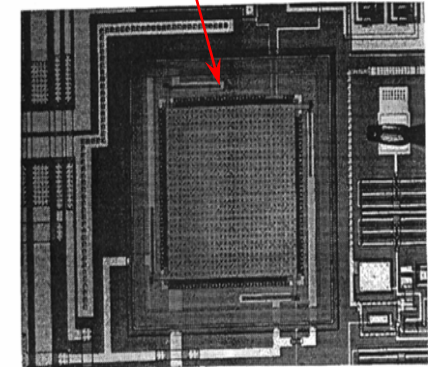
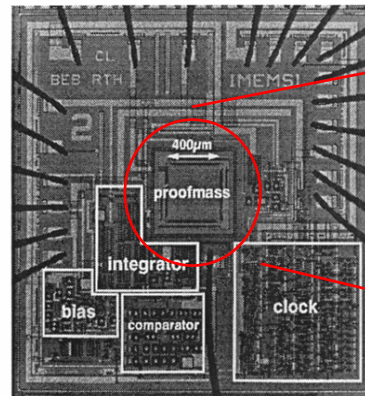
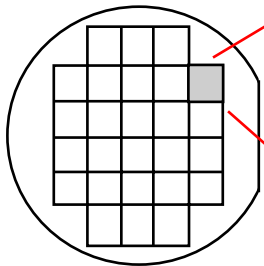


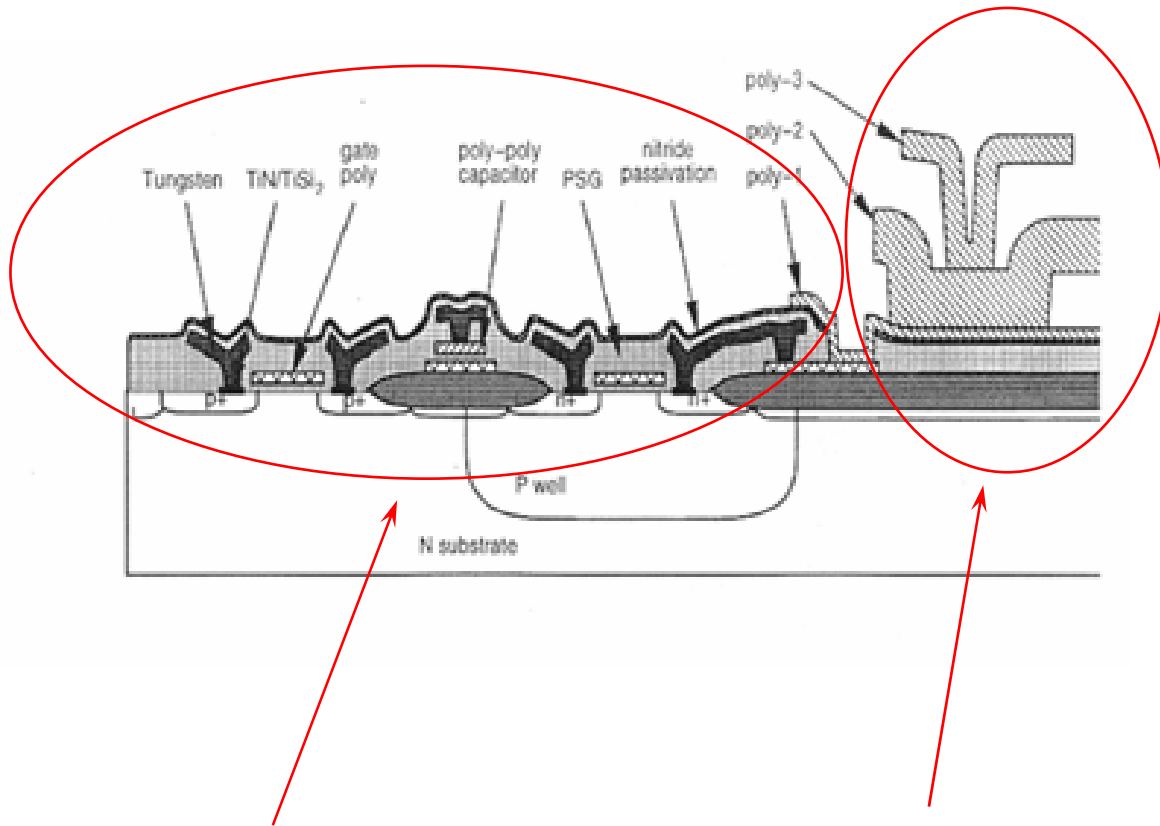
- MEMS: Integration of electronic and mechanical components on a same chip



Electronic part

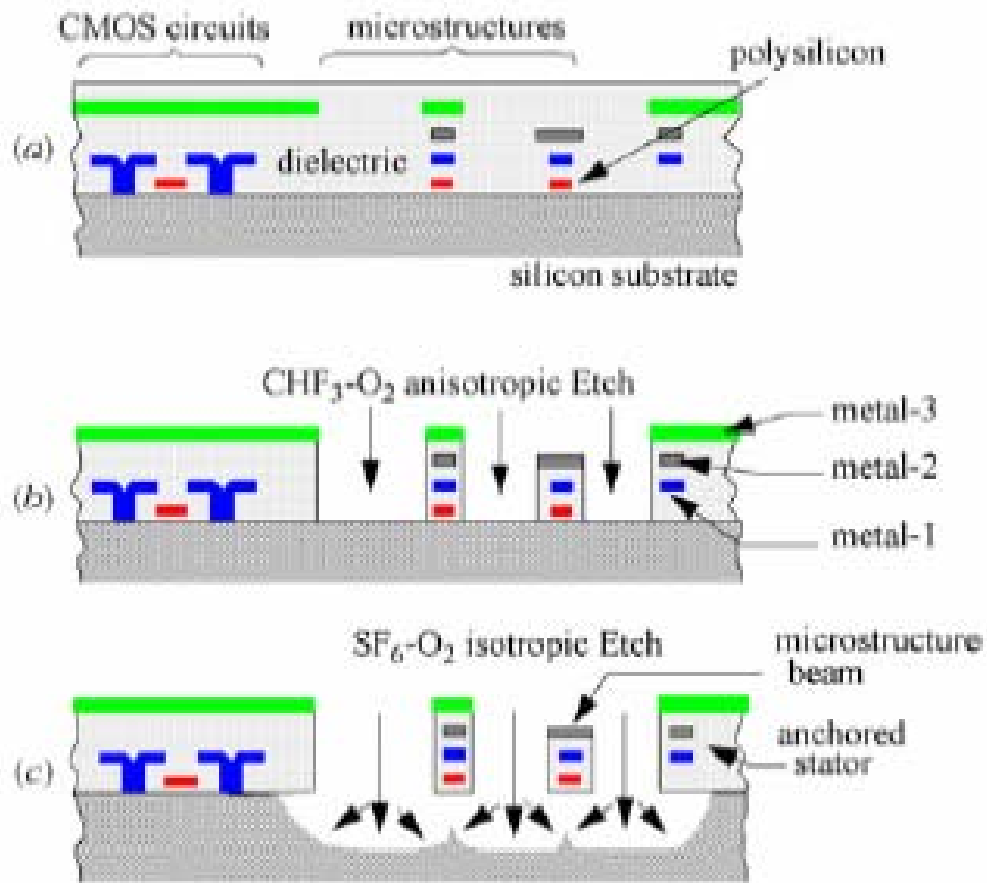
Mechanical part





Electronics part

Mechanical part



H. Lakdawala and G. K. Fedder, CMU, 2004

